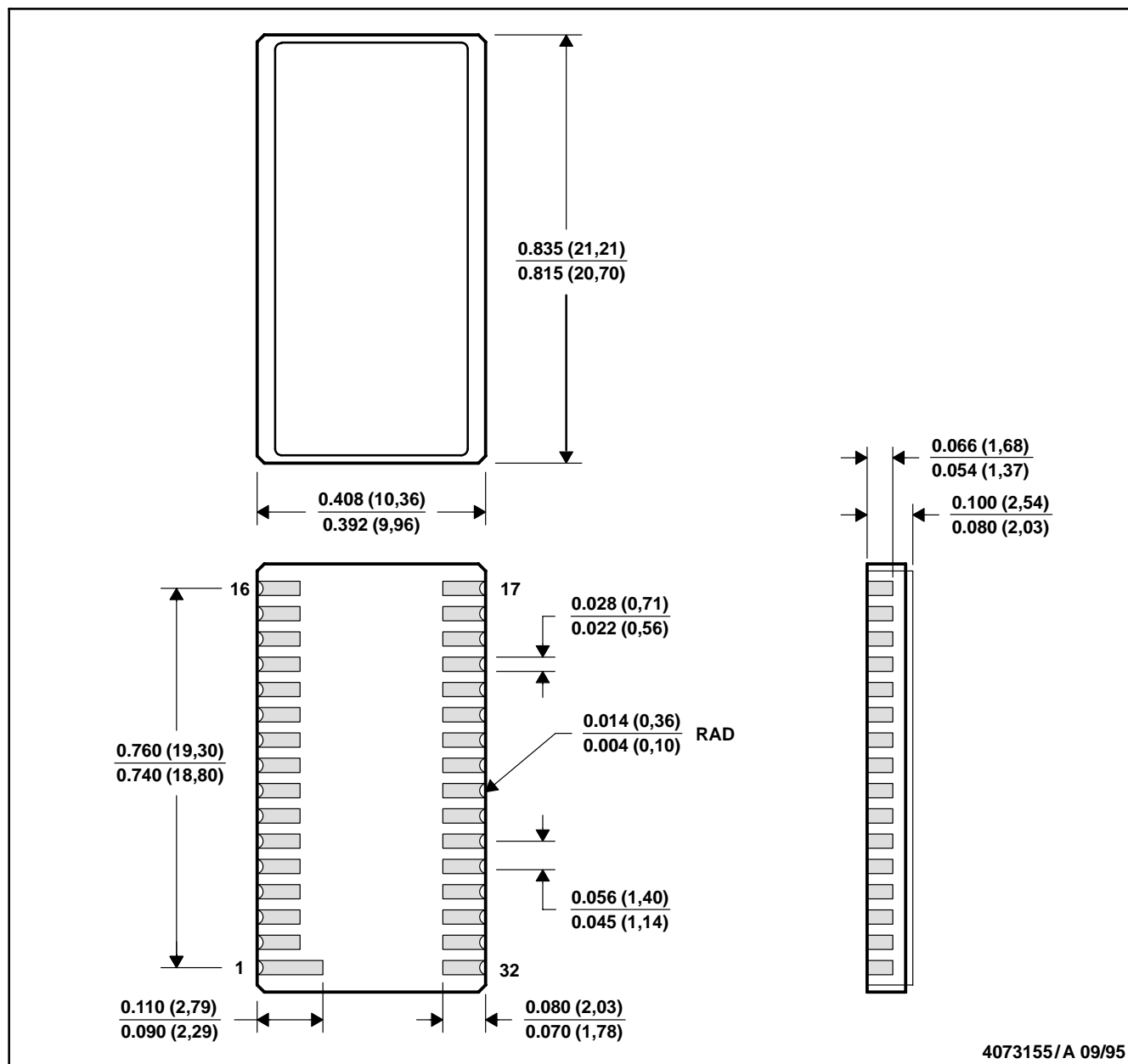


FJC (R-CDCC-N32)

LEADLESS CERAMIC CHIP CARRIER



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Index mark may appear on top or bottom depending on package vendor.

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